

# **30V N-Channel Trench MOSFET**

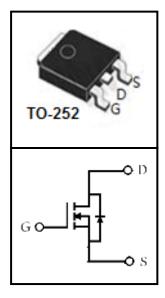
#### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information			
Device	Package	Marking	
CTD03N005	TO-252	CTD03N005	

<b>Absolute Maximum Ratings</b> at T <sub>j</sub> = 25°C unless otherwise noted					
Parameter		Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)		V <sub>DSS</sub>	30	V	
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)		85	А	
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)	I <sub>D</sub>	60	A	
Pulsed Drain Current	(note2)	I <sub>DM</sub>	350	А	
Gate Source Voltage		V <sub>GSS</sub>	±20	V	
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	92	mJ	
Power Dissipation T <sub>C</sub> = 25°C	(note4)	P <sub>D</sub>	87	W	
Operating Junction and Storage Temperature Range		$T_J, T_stg$	-55~175	°C	

Thermal Characteristics				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-Case	(note1)	$R_{ heta JC}$	1.72	°C/W



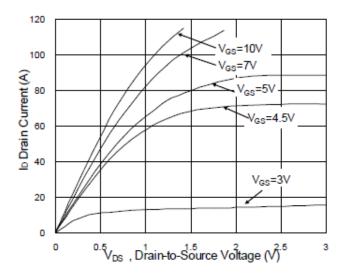
Electrical Characteristics T <sub>j</sub> = 25°C unless otherwise specified							
Danier of an			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	-		٧	
Zero Gate Voltage Drain Current		$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
Zeio Gate Voltage Diain Current	I <sub>DSS</sub>	$V_{DS} = 24V, V_{GS} = 0V, T_{J} = 100^{\circ}C$		-	5	uA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	V	
Drain-Source On-Resistance (note2)	Б	$V_{GS} = 10V, I_D = 30A$		3.7	5	mΩ	
Diam-Source On-Nesistance (note2)	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_{D} = 20A$		6	9	mΩ	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ ,		1259		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 0V,$ $V_{DS} = 15V,$ $f = 1.0MHz$		206			
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0MHZ		198			
Total Gate Charge	$Q_g$			13			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10V, I_{D} = 12A,$ $V_{GS} = 4.5V$		1.8		nC	
Gate-Drain Charge	$Q_gd$			6.5			
Turn-on Delay Time	t <sub>d(on)</sub>			7.5			
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = 15V$ , $V_{GS} = 4.5V$ , $R_{G} = 3\Omega$ ,		14.5		ns	
Turn-off Delay Time	$t_{d(off)}$	$V_{GS} = 4.5V, R_G = 3\Omega, R_L = 0.75\Omega$		33.0			
Turn-off Fall Time	t <sub>f</sub>			10.3			
Body Diode Characteristics							
Continuous Body Diode Current	I <sub>S</sub>	T 050			85		
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °c			350	Α	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 20A$ , $V_{GS} = 0V$			1.2	V	

#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width≤300us , duty cycle≤2%
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.5mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



**Fig.1 Typical Output Characteristics** 

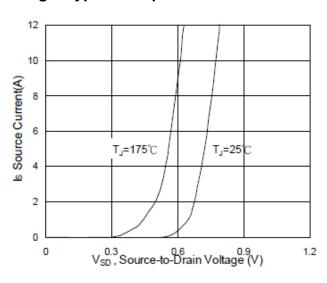
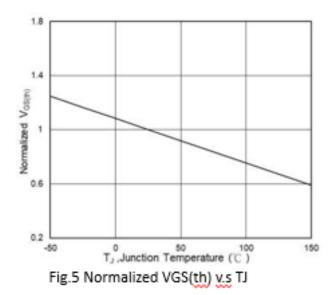


Fig.3 Forward Characteristics of Reverse Diode



Out-Resistance (mg)

ID=30A

VGS, Gate—to-Source Voltage(V)

Fig.2 On-Resistance vs. G-S Voltage

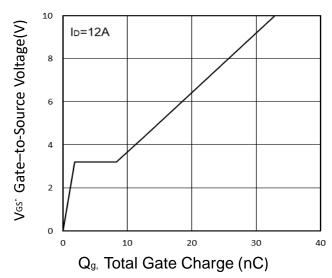


Fig.4 Gate-Charge Characteristics

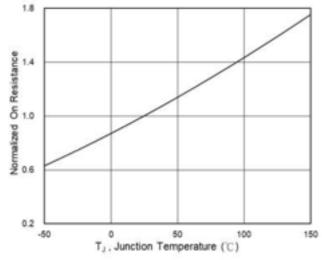


Fig.6 Normalized RDSON v.s TJ



## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

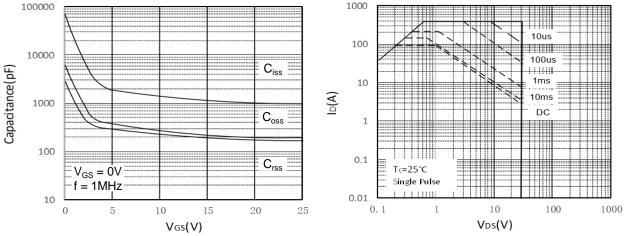


Fig.7 Capacitance

Fig.8 Safe Operating Area

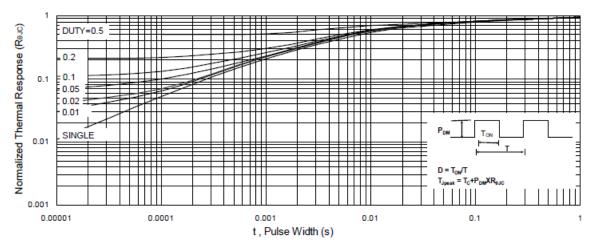


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

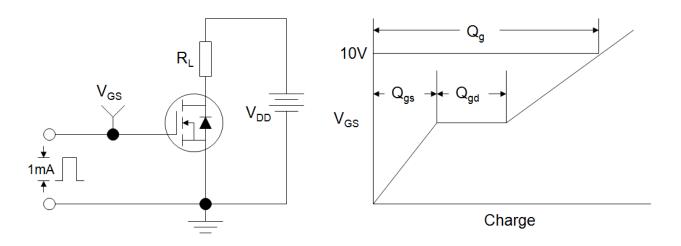


Figure B: Resistive Switching Test Circuit and Waveform

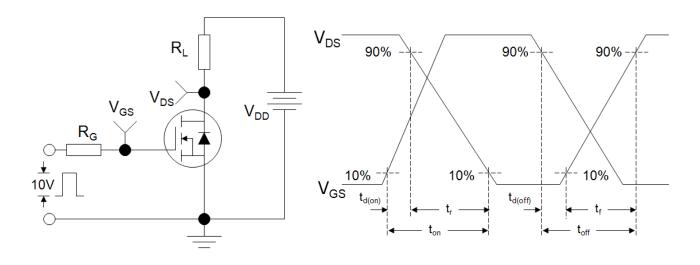
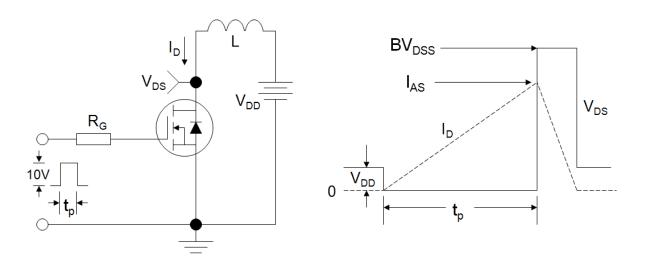
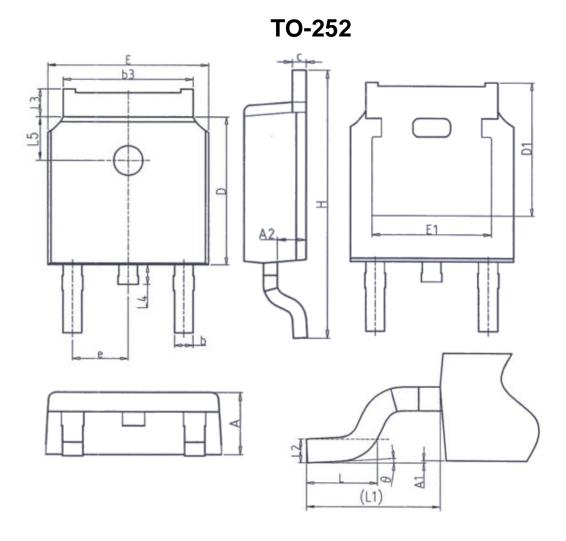


Figure C: Unclamped Inductive Switching Test Circuit and Waveform







Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	_		

Unit: mm				
Symbol	Min. Max.			
е	2. 286BSC			
Н	9. 40	10.50		
L	1. 38	1. 75		
L1	2. 90REF			
L2	0. 51BSC			
L3	0.88	1. 28		
L4	_	1.00		
L5	1. 65	1. 95		
θ	0°	8°		



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